



10/082372

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Michael E. Connell et al.

Examiner: Andre C Stevenson

Patent No.: 7,169,685

Group Art Unit: 2812

Issue Date: January 30, 2007

Docket No: 2269-5083US

Title: WAFER BACK SIDE COATING TO BALANCE STRESS FROM PASSIVATION LAYER ON  
FRONT OF WAFER AND BE USED AS A DIE ATTACH ADHESIVE

Commissioner for Patents  
Office of Patent Publication  
ATTN: Certificate of Correction Branch

**Certificate**  
DEC 31 2007  
**of Correction**

We are transmitting herewith the attached:

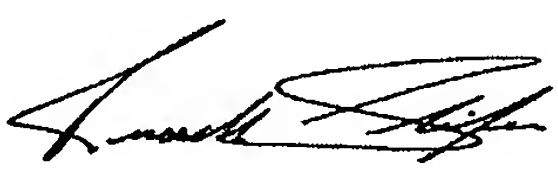
- ☒ Request for Certificate of Correction.
- ☒ Certificate of Correction Form - PTO-1050 (in duplicate)
- ☒ A return postcard.

**Please charge any additional fees or credit overpayment to Deposit Account No. 13-3092.**

Customer Number: 26809

Respectfully submitted,

Date: December 21, 2007

By:   
Russ Sliter  
Reg. No. 39,838

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents and Trademarks, P.O. Box 1450, Alexandria VA 22313-1450, on this 21<sup>st</sup> day of December 2007.

Christine Hartness

\_\_\_\_\_  
Name



\_\_\_\_\_  
Signature

**IN UNITED STATES PATENT AND TRADEMARK OFFICE**

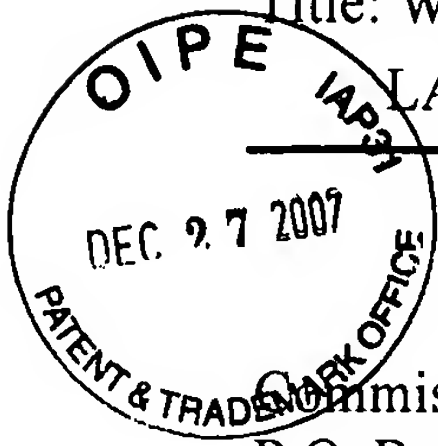
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Patentee: Michael E. Connell et al.

Title: WAFER BACK SIDE COATING TO BALANCE STRESS FROM PASSIVATION  
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**REQUEST FOR CERTIFICATION OF CORRECTION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
ATTN: Certificate of Correction Branch

It is requested that a Certificate of Correction be issued correcting printing errors appearing in the above-identified United States patent. Two copies of the text of the Certificate in the suggested form are enclosed.

**As the error is that of the Patent Office, it is believed that no fee is due.**

Issuance of the Certificate of Correction would neither expand nor contract the scope of the claims as properly allowed, and re-examination is not required.

Respectfully submitted,

**Customer Number: 26809**

Date: December 21, 2007

By:

A handwritten signature in black ink, appearing to read "Russ Sliter".

Russ Sliter  
Reg. No. 39,838

CERTIFICATE UNDER 37 CFR § 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on this 21<sup>st</sup> day of December 2007

Christine Hartness

A handwritten signature in black ink, appearing to read "Christine Hartness".

\_\_\_\_\_  
Name

\_\_\_\_\_  
Signature

## UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO : 7,169,685

Page (1) of 1

DATED : January 30, 2007

INVENTOR(S) : Connell et al.

It is certified that errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the face page, in "Assistant Examiner", in column 2, line 1, delete "AndréC. Stevenson" and insert - - André C. Stevenson - -, therefor.

On the face page, in field (57), under "Abstract", in column 2, line 6, after "attach" delete ",".

On the face page, in field (57), under "Abstract", in column 2, line 7, delete "enhance" and insert - - enhanced - -, therefor.

In column 11, line 1, in Claim 1, delete "semiconductor" and insert - - semiconductive - -, therefor.

In column 11, lines 7-8, in Claim 1, delete "semiconductor" and insert - - semiconductive - -, therefor.

In column 11, line 10, in Claim 1, delete "semiconductor" and insert - - semiconductive - -, therefor.

In column 11, line 22, in Claim 6, after "said" insert - - nonwarped - -.

In column 11, line 31, in Claim 8, delete "semiconductor" and insert - - semiconductive - -, therefor.

In column 12, line 36, in Claim 28, after "said" insert - - nonwarped - -.

In column 12, lines 63-64, in Claim 33, delete "semiconductive" and insert - - semiconductor - -, therefor.

In column 13, line 31, in Claim 41, delete "portion" and insert - - portions - -, therefor.

In column 13, line 33, in Claim 41, delete "semicondutor" and insert - - semiconductor - -, therefor.

In column 14, line 13, in Claim 55, delete "SM" and insert - - SIMM - -, therefor.

In column 15, line 12, in Claim 65, delete "semiconductive" and insert - - semiconductor - -, therefor.

In column 15, line 20, in Claim 65, delete "semicondutor" and insert - - semiconductor - -, therefor.

In column 16, line 26, in Claim 73, delete "comprises" and insert - - comprise - -, therefor.